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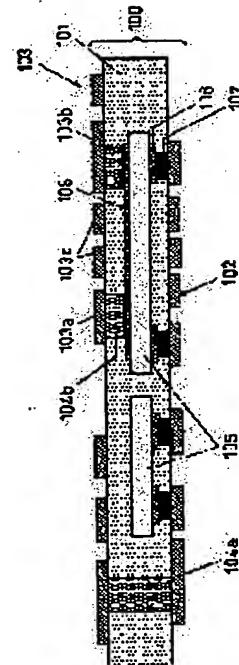
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(54) CIRCUIT BOARD AND METHOD OF PRODUCTION

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a circuit board in which high density mounting can be effected without lowering the containing rate of wiring.

SOLUTION: Containing rate of wiring is enhanced by forming an auxiliary wiring pattern 108 in a component surface region not pertaining to external connection of an electronic component 105 provided in a board, and connecting the auxiliary wiring pattern 108 electrically with wiring patterns of board 103, 102 thereby using the auxiliary wiring pattern 108 as the wiring patterns of board 103, 102.



LEGAL STATUS

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